

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-13 (Canceled):

Claim 14 (Original): A method of manufacturing a chip carrier film comprising the steps of:

etching a metal film formed on a surface of a base film to form a metal wiring;
coating a first insulating film to cover the metal wiring;
mounting a semiconductor chip on the base film to be connected to the metal wiring;
coating a back face of the base film with a second insulating film having a different coefficient of curing shrinkage from that of the first insulating film; and
curing the first and second insulating films.

Claim 15 (Original): The method of Claim 14, wherein the second insulating film having has a high higher coefficient of curing shrinkage than that of the first insulating film is coated with these, and the first and second insulating films are cured.

Claim 16 (Currently Amended): The method of any one of Claims Claim 14 to 15, wherein the first insulating film and the second insulating film are cured by heating.

Claims 17-24 (Canceled).

Claim 25 (New): The method of Claim 15, wherein the first insulating film and the second insulating film are cured by heating.